

3.2x2.8mm PLCC2 SMD LED

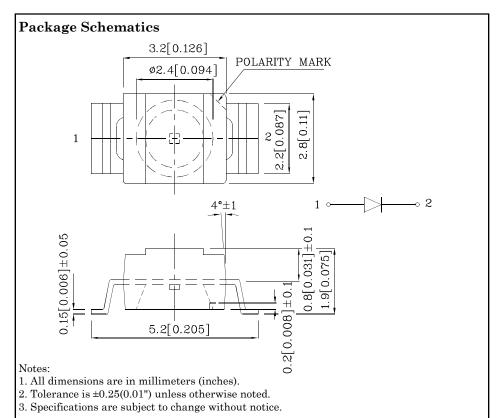


Features

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Standard Package: 2000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant







Absolute Maximum Ratings (T _A =25°C)		UR (GaAsP/ GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	160	mA	
Power Dissipation	P_{D}	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	C	

Operating Characteristics (T _A =25°C)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λР	627 627*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =20mA)	λD	625 617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	45	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* λP nm	Viewing Angle 20 1/2
				min.	typ.		
XZUR45S-9	Red	GaAsP/GaP	Water Clear	12 8*	24 12*	627*	120°

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Oct 31,2012 XDSB4886 V3-X Layout: Maggie L.

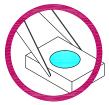


Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

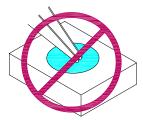
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

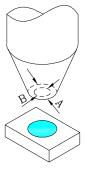




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



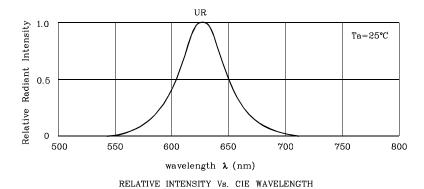
- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

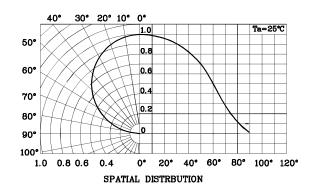


5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of lead-frame. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

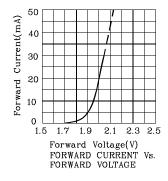


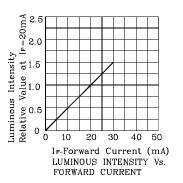


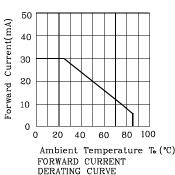


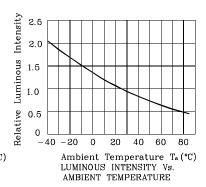


\$ UR



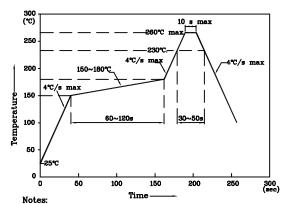






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



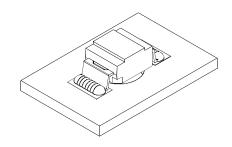
- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions



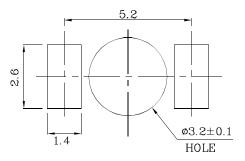


❖ The device has a single mounting surface. The device must be mounted according to the specifications.

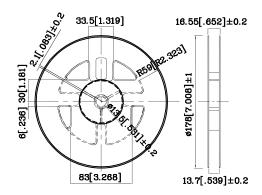
www.SunLEDusa.com



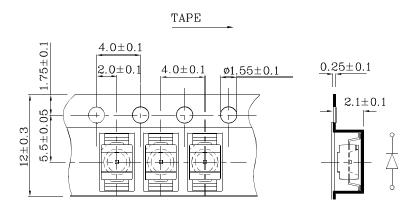
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



* Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS

